

# NUP8010MN

## Low Capacitance Transient Voltage Suppressor Array

This integrated transient voltage suppressor device (TVS) is designed for applications requiring transient overvoltage protection. It is intended for use in sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its integrated design provides very effective and reliable protection for eight separate lines using only one package. These devices are ideal for situations where board space is at a premium.

### Features

- Low Capacitance
- Low Leakage Current < 1  $\mu$ A @ 3 V
- ESD Ratings:
  - ♦ IEC61000-4-2, 8 kV (Contact)
  - ♦ IEC61000-4-2, 15 kV (Air)
  - ♦ Machine Model = Class C, 400 V
  - ♦ Human Body Model = Class 3B, 8 kV
- DFN Package, 1.6 x 1.6 mm
- Moisture Sensitivity Level 1
- This is a Pb-Free Device

### Benefits

- Provides Protection for ESD Industry Standards: IEC 61000, HBM
- Protects the Line Against Transient Voltage Conditions in Either Direction
- Minimize Power Consumption of the System
- Minimize PCB Board Space

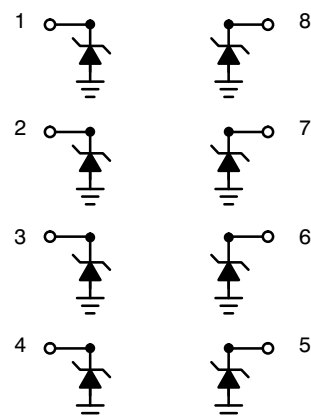
### Applications

- ESD Protection for Data Lines
- Wireless Phones
- Handheld Products
- Notebook Computers
- LCD Displays

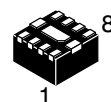


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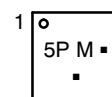


(Top View)



DFN8  
CASE 506AK

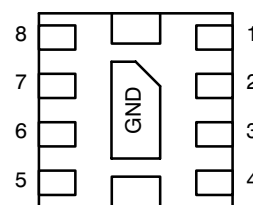
### MARKING DIAGRAM



5P = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### PIN CONNECTIONS



(Bottom View)

### ORDERING INFORMATION

Device	Package	Shipping
NUP8010MNT1G	DFN8 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NUP8010MN

## MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
ESD Discharge IEC61000-4-2 Air Discharge Contact Discharge	$V_{PP}$	15 8.0	kV
Peak Power Dissipation (8 x 20 $\mu$ S @ $T_A = 25^\circ\text{C}$ )	$P_{pk}$ (Note 1)	20	W
Operating Temperature Range	$T_{OP}$	-40 to 85	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Maximum Lead Temperature for Soldering Purposes (1.8 in from case for 10 seconds)	$T_L$	260	$^\circ\text{C}$

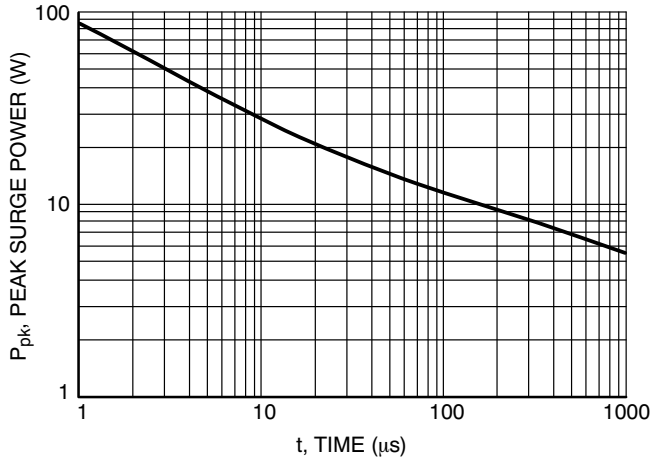
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Nonrepetitive current per Figure 4.

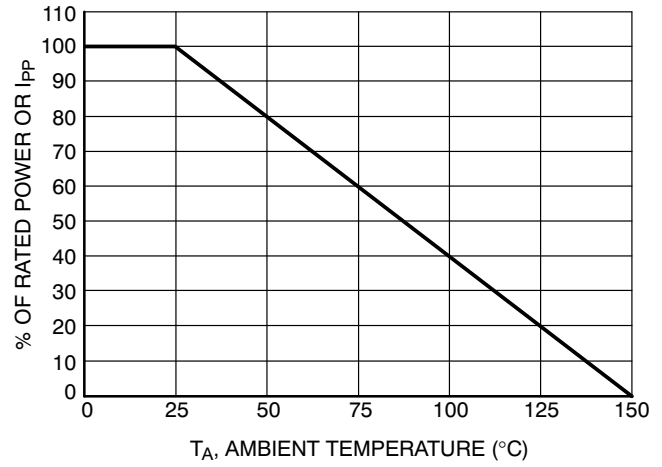
## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Reverse Working Voltage	$V_{RWM}$				3.0	V
Breakdown Voltage	$V_{BR}$	$I_R = 1.0 \text{ mA}$	5.3	5.6	5.9	V
Leakage Current	$I_R$	$V_{RWM} = 3.3 \text{ V}$		0.01	1.0	$\mu\text{A}$
Clamping Voltage	$V_c$	$I_{PP} = 1.6 \text{ A}$			13	V
Capacitance	$C_d$	$f = 1 \text{ MHz}, V_R = 0 \text{ V}$		13	17	pF
Capacitance	$C_d$	$f = 1 \text{ MHz}, V_R = 3.0 \text{ V}$		7.0	11.5	pF

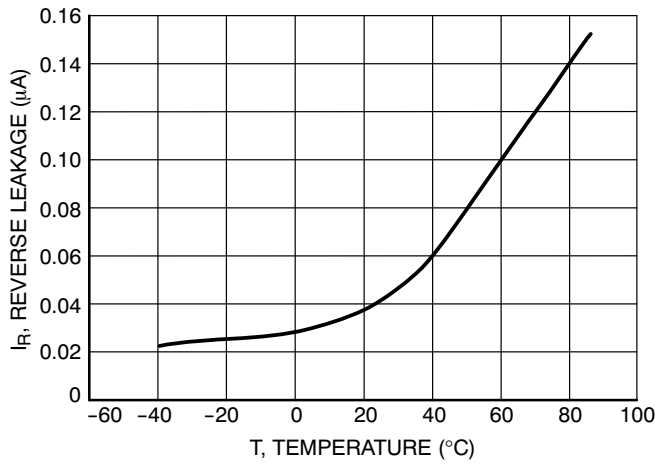
**TYPICAL PERFORMANCE CURVES** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)



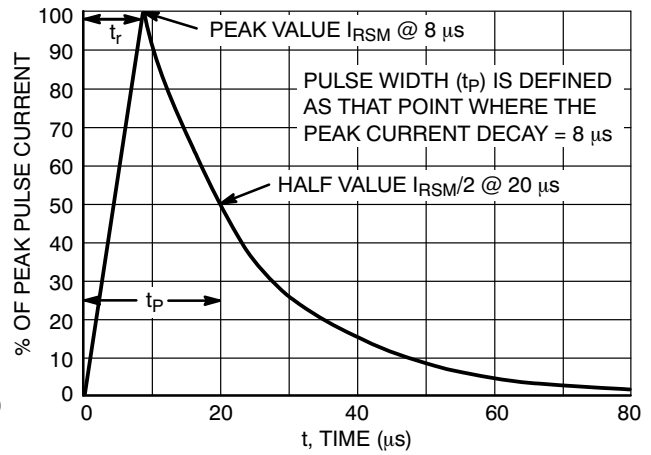
**Figure 1. Pulse Width**



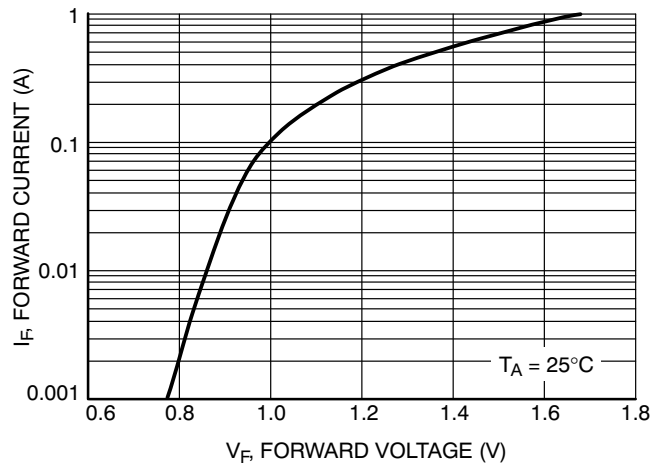
**Figure 2. Power Derating Curve**



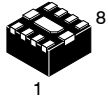
**Figure 3. Reverse Leakage versus Temperature**



**Figure 4.  $8 \times 20 \mu\text{s}$  Pulse Waveform**



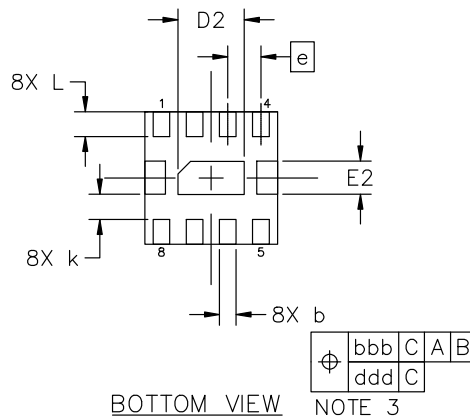
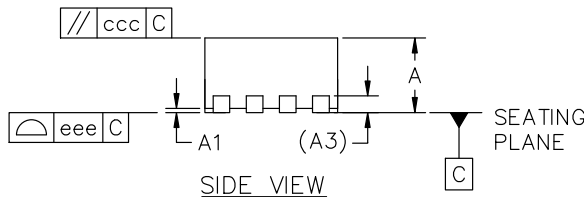
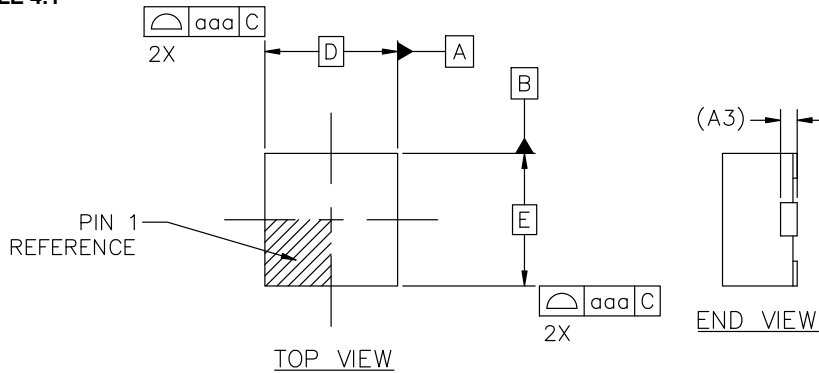
**Figure 5. Forward Voltage**



SCALE 4:1

**DFN8 1.60x1.60x0.90, 0.40P**  
**CASE 506AK**  
**ISSUE D**

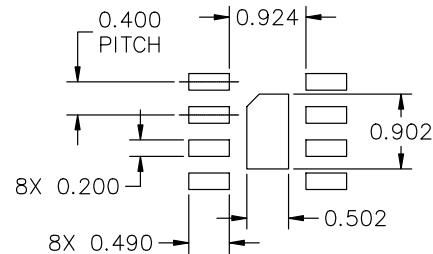
DATE 03 JUL 2025



MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	---	0.05
A3	0.20 REF		
b	0.15	0.20	0.25
D	1.60 BSC		
D2	0.70	0.80	0.90
E	1.60 BSC		
E2	0.30	0.40	0.50
e	0.40 BSC		
k	0.20	---	---
L	0.20	0.30	0.40
POSITION FORM & TOLERANCE			
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		

**NOTES:**

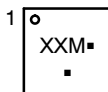
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



**RECOMMENDED MOUNTING FOOTPRINT**

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



X = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>DFN8 1.60x1.60x0.90, 0.40P</b>	<b>PAGE 1 OF 1</b>

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